## COMBINED DECLARATION AND POWER OF ATTORNEY FOR PATENT COOPERATION TREATY APPLICATION (Page 1)

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

		d sole inventor (if only one n		
		pelow) of the subject matter v	which is claimed and fo	or which a patent is
sought on the invention		NEODIOVOLE 3 CDIDOC	VOLONI KANE DEDI	172 M T 17E U
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2002 and was are	nich was nied as PCI i	nternational Application No.	PC1/JP03/08478	on <u>03 July,</u>
	nded under PCT Article applicable).	= 19 On		
(n	applicable).			
I hereby sta	ate that I have reviewed as amended by any ame	and understand the contents ndment referred to above.	of the above identified	specification,
I acknowle	dge the duty to disclose	information which is materia	al to patentability as de	fined in 37 CFR §
application(s) for pate country other than the application(s) for pate country other than the	ent or inventor's certific United States of Amer ent or inventor's certific	efits under Title 35, United Sate or of any PCT internation ica listed below and have alsate or any PCT international ica filed by me on the same sclaimed:	al application(s) design o identified below any application(s) designat	nating at least one foreign ing at least one
Country	Application No.	Filed (Day/Mo./Yr.)	Priority Clair	med (Yes/No)
Japan	2002-194273	03 July 2002	Yes	
I hereby cl listed below.	aim the benefit under T	itle 35, United States Code, §	120 of any United Sta	tes application(s)
Application N	o. Filed (Da	y/Mo./Yr.)	Status (Patented, Pending, Abandoned)	
		associated with the firm and o		

FITZPATRICK, CELLA, HARPER & SCINTO Customer Number: 05514

direct that all correspondence be addressed to the address associated with that Customer Number:

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

## COMBINED DECLARATION AND POWER OF ATTORNEY FOR PATENT COOPERATION TREATY APPLICATION (Page 2)

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